



FLY-801 T

Top LED Wire bonder

Product descriptions and features

Features

- Thermosonic high speed bonding, fast conversion
- Vision system: Programmable look ahead PR
- Multiple die and level bonding capability
- Ease of maintenance
- Competitive pricing

Wire Type

Au, Ag, Cu, CuPd, alloy

Applied Range

LED industry



KEJIE website

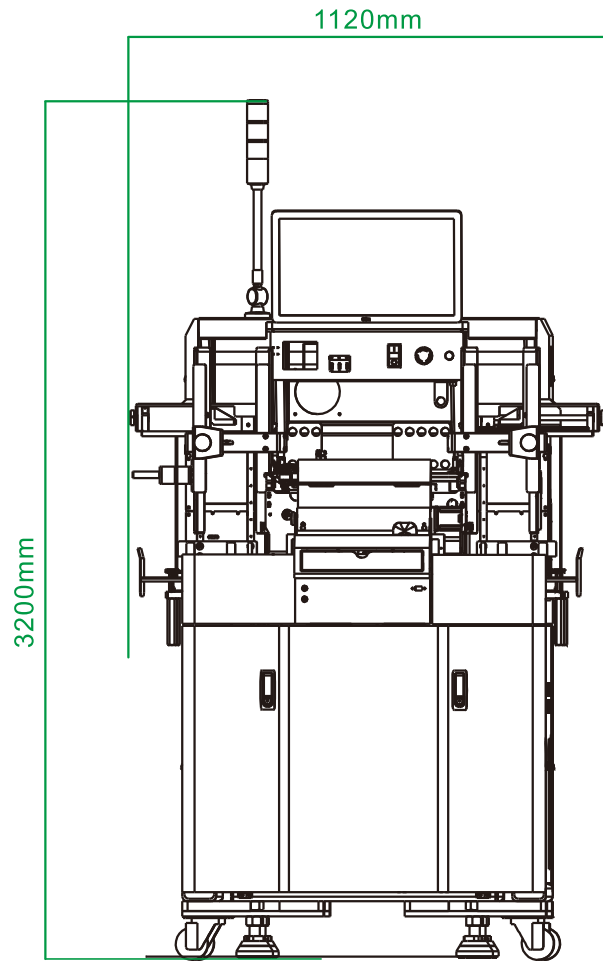


KEJIE wechat

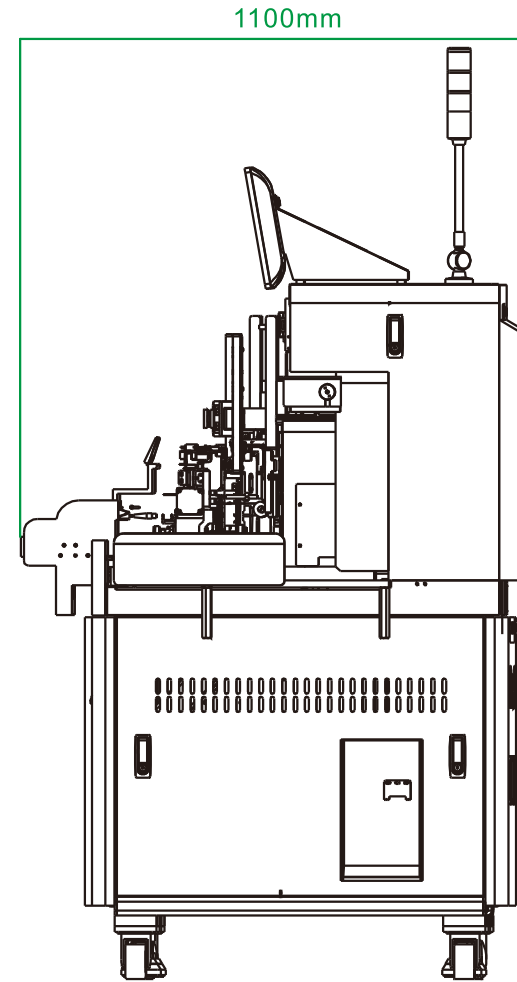
Parameters

Item	Parameter
Bonding Technology	Thermosonic bonding
Optics	Single path
Bonding Accuracy	$\pm 3.0\mu\text{m}$
Bonding area	56x70mm
Cycle time	65ms/wire
Wire diameter	18 μm -50 μm

Machine dimension



Front



Left